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SMD22PL THRU SMD26PL

Schottky Barrier Diodes
20 to 60 Volts

Features

- High Surge Capability
- Low Forward Voltage
- Low Profile Package
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0

Mechanical Data

- Packaging:Powerlite-123
- Marking Code : SMD22PL---M2
  SMD24PL---M4
  SMD26PL---M6

Maximum Ratings

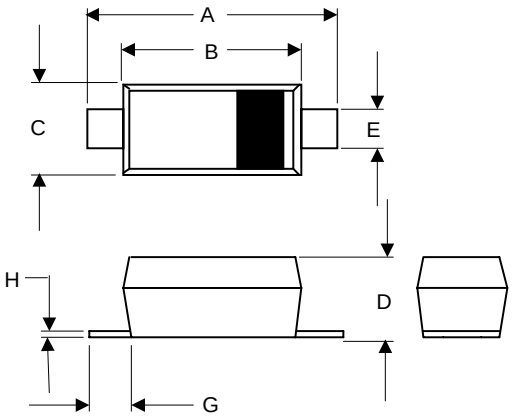
Symbol	Rating		Rating	Unit
V_{RMS}	Maximum RMS Voltage	SMD22PL SMD24PL SMD26PL	14 28 42	V
V_{RRM}	Repetitive Peak Reverse Voltage	SMD22PL SMD24PL SMD26PL	20 40 60	V
$I_{F(AV)}$	Rectified Current (Average) Half Wave Rectification with Resist. Load at T_L=90°C		2.0	A
I_{FSM}	Surge Forward Current,halfsine wave 8.3ms		50	A
R_{thJL}	Typical Thermal Resistance(1)		80	°C / W
T_J	Junction Temperature		-65 to +125	°C
T_{STG}	Storage Temperature		-65 to +125	°C

Electrical Characteristics @ 25°C Unless Otherwise Specified

Symbol	Parameter		Min	Typ	Max	Units
V_F	Forward Voltage (@2A dc)	SMD22PL	---	---	0.50	V
		SMD24PL	---	---	0.50	
		SMD26PL	---	---	0.70	
I_R	Maximum DC Reverse Current		---	---	0.5	mA
C_j	Typical Junction Capacitance @f=1.0MHz,Vr=4V		---	210	---	pF

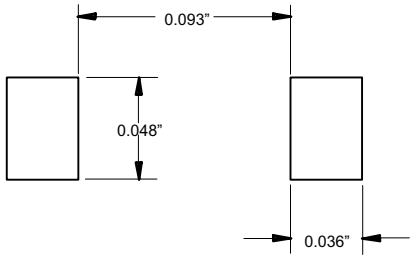
Tnote:Thermal Resistance:PC Board Mounted on 0.2*0.2"(5*5mm) copper pad area.

Powerlite-123



DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	.140	.152	3.55	3.85	
B	.100	.112	2.55	2.85	
C	.055	.071	1.40	1.80	
D	.037	.053	0.95	1.35	
E	.020	.039	0.50	1.00	
G	.010	-----	0.25	-----	
H	-----	.008	----	.20	

SUGGESTED SOLDER PAD LAYOUT



SMD22PL~SMD26PL

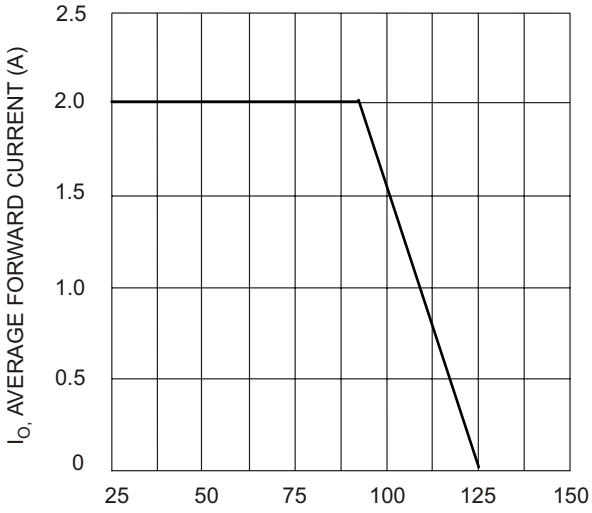


Fig. 1 Forward Current Derating Curve

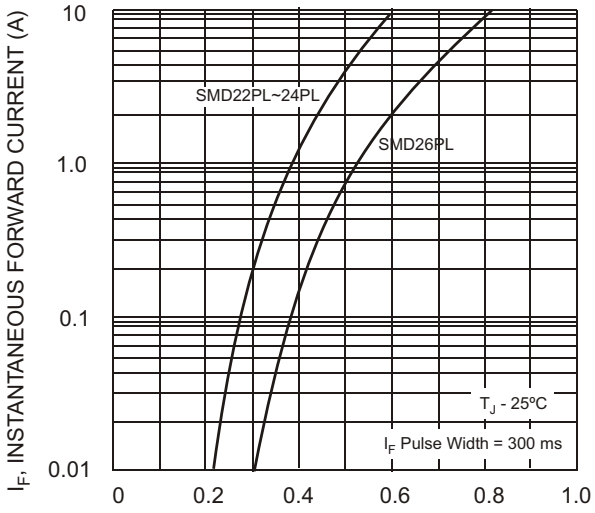


Fig. 2 Typical Forward Characteristics

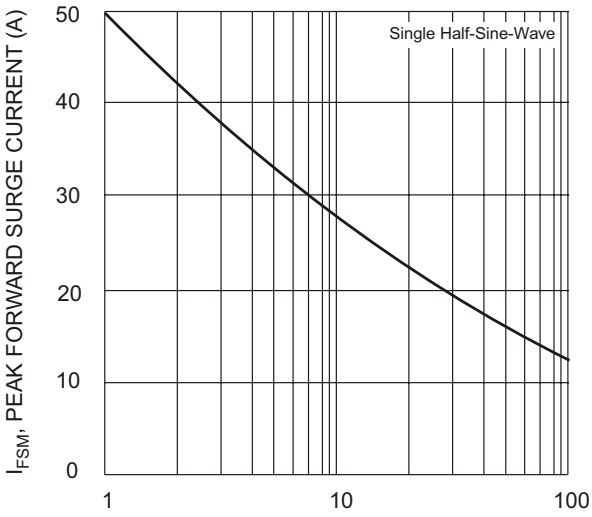


Fig. 3 Max Non-Repetitive Peak Forward Surge Current

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